

Material Composition Declaration

iS20M028S1PQ

Company Name:	iDEAL Semiconductor Devices, Inc.
Quality Contact:	Deo Laranang
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Part Weight:	1,905.7711 mg

Material	Composition	CAS No.	% of weight	Weight (mg)
Wafer	Silicon	7440-21-3	100	2.7261
Lead Frame	Cu	7440-50-8	>99.8	1,242.30
	Fe	7439-89-6	0.05~0.15	
	P	7723-14-0	0.025~0.04	
	Ni	7440-02-0	0.0023~0.0058	
Solder	Pb	7439-92-1	92.3~92.7	2.2110
	Sn	7440-31-5	4.9~5.1	
	Ag	7440-22-4	2.4~2.6	
Wire	Al	7429-90-5	>99.99	3.2150
	Ni	7440-02-0	<60ppm	
	Si	7440-21-3	<10ppm	
	Fe	7439-89-6	<3ppm	
	Mg	7439-95-4	<3ppm	
	Cu	7440-50-8	<3ppm	
	B	7440-42-8	<1ppm	
	Ag	7440-22-4	<1ppm	
	Mn	7439-96-5	<1ppm	
	Ca	7440-70-2	<1ppm	
	Cr	7440-47-3	<1ppm	
	Al	7429-90-5	≥99.99	0.0990
	The others	—	≤0.01	
Mold Compound	Formaldehyde, polymer with (chloromethyl)oxirane and 2-methylphenol	29690-82-2	10~20	645.44
	Phenol Resin	9003-35-4	1~5	
	Silica(Amorphous)	60676-86-0	60~80	
	Metal Hydroxide	Trade Secret	5~10	
	Carbon black	1333-86-4	0.1~1	
Plating	Tin	7440-31-5	99.90	9.7800

	Other		<0.1	
Total Weight				1905.7711

Note: The substance content disclosed herewith is approximate and is based on engineering calculations. Statements are based on our present knowledge and may be subject to change at any time due to technical requirements and development. iDEAL Semiconductor may update this document without notification. Statement may not include information regarding the minute quantities of dopant and metal materials in the electrical devices contained within the finished product.